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**U. S. PATENT DOCUMENTS**

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE*

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS**

EXAMINER INITIAL		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
AC		"Micro-ball Bump Technology For Fine-pitch Interconnections", Shimokawa K; Tatsumi K; Hashino E; Ohzeki Y; Konda M; Kawakami Y; Conference Proceedings Article 1 <sup>st</sup> 1997 IEMT/IMC Symposium (IEEE Cat. No. 97CH36059), Proceedings of 1997 First International Electronic Manufacturing Technology (IEMT) IMC Symposium, Tokyo, Japan, 16-18 April 1997; ISBN 0-7803-4235-6, pages 105-109.

EXAMINER	<i>Alonso Chambliss</i>	DATE CONSIDERED	5/16/03
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

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